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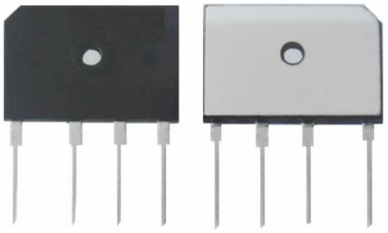

RS35MH Material Safety Data Sheet

Material Content Declaration

Material name	Substance name e.g. Copper (Cu), Gold (Au)	CAS no., if known	Substance mass (mg)	% OF Weight (%)	ppm Of Total Weight
Lead Frame 32.72%	Copper (Cu)	7440-50-8	2,620.000	100.00	327,222.5
	Total		**2,620**		
Solder paste 0.57%	Lead (Pb)	7439-92-1	42.55	92.50	5,314.2
	Tin (Sn)	7440-31-5	2.3	5.00	287.3
	Silver (Ag)	7440-22-4	1.15	2.50	143.6
	Total		**46**		
Dice 0.21%	Silicon (Si)	7440-21-3	16.128	96	2,014.3
	Nickel (Ni)	7440-02-0	0.336	2	42.0
	Lead (Pb)	7439-92-1	0.336	2	42.0
	Total		**16.8**		
Aluminum substrate 19.36%	Calcined clay	66402-68-4	50.065	3.23	6,252.8
	Aluminum	7429-90-5	1499.935	96.77	187,333.0
	Total		**1,550**		
Molding 46.95%	Cristobalite	14464-46-1	3119.97	83	532,140.4
	Epoxy resin	29690-82-2	214.26	5.70	36,544.6
	Phenolic resin	9003-35-4	300.72	8	51,290.6
	Antimony trioxide(Sb2	1309-64-4	11.277	0.3	1,923.4
	Brominated epoxy res	40039-93-8	75.18	2	12,822.7
	Carbon Black	1333-86-4	37.59	1	6,411.3
	Total		**3,759.0**		
Plating 0.19%	Tin (Sn)	7440-31-5	14.985	100.00	1,871.5
	Total		**14.99**		
	Total mass (mg)		**8,006.785**		